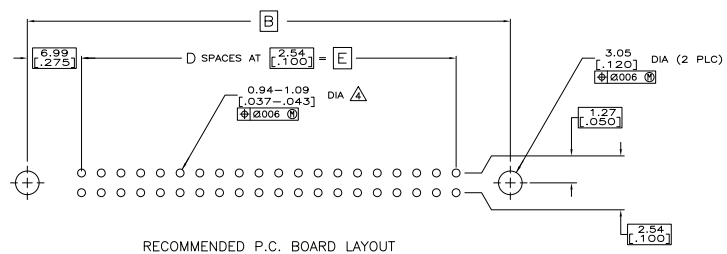
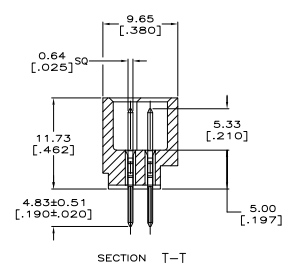
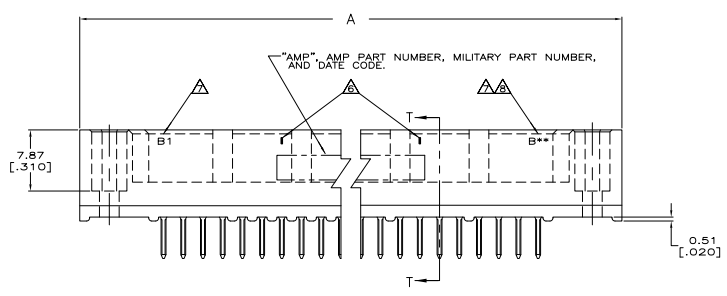
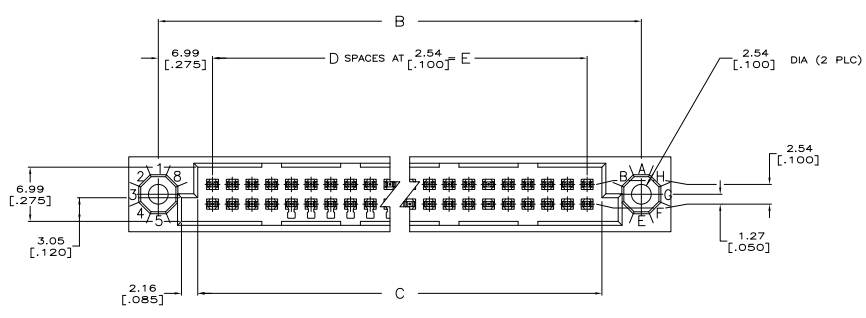


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REV	DATE	DESCRIPTION	BY	APP
AD 25		REVISED PER ECD-11-008907	2240111 HMR	AS



RECOMMENDED P.C. BOARD LAYOUT

THIS DRAWING IS A CONTROLLED DOCUMENT.		APPROVED BY	DATE	TE Connectivity	
DRAWN BY		DATE	HDI, 2 ROW, PIN ASSEMBLY, 4.83 [.190] LONG SOLDER PINS, 00076 [000000] GOLD PLATE		
CHECKED BY		DATE	A1 00779 G=633903		
CUSTOMER DRAWING		DATE	REV	1	2

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REV	DATE	DESCRIPTION	BY	APP
AD	25	SEE SHEET 1	-	-

- △ HOUSING MATERIAL: THERMOPLASTIC, COLOR-NATURAL.
- △ CONTACT MATERIAL: PHOSPHOR BRONZE.
- △ CONTACT FINISH: .00127-.00254 [.000050-.000100] NICKEL UNDERPLATE ALL OVER; .00127 [.000050] GOLD PLATE IN CONTACT AREA, TIN-LEAD PLATED POSTS.
- △ SOLDER PIN POST RECOMMENDED P.C. BOARD HOLE SIZES ARE 0.94-1.09 [.037-.043]; RECOMMENDED PAD DIA IS 1.52 [.060].
- 5. DIMENSIONS IN BRACKETS ARE IN INCHES.
- △ MARK EVERY TENTH POST POSITION.
- △ MARK ROW B AND FIRST-LAST POSITION IDENT. NUMBER PER AMP SPEC. 115-9063.
- △ TOTAL NUMBER OF POSITIONS PER ROW.

NOTES	MILITARY PART NUMBER	E	D	C	B	A	POSN	PART NUMBER
-	N/A	137.16 [5.400]	54	140.97 [5.550]	151.13 [5.950]	158.75 [6.250]	110	1-533903-1
-	M55302/173-150	187.86 [7.400]	74	191.77 [7.550]	201.93 [7.950]	209.55 [8.250]	150	1-533903-0
-	M55302/173-87	124.46 [4.900]	49	128.27 [5.050]	138.43 [5.450]	146.05 [5.750]	100	533903-8
-	-	73.66 [2.900]	29	77.47 [3.050]	87.63 [3.450]	95.25 [3.750]	60	533903-6
-	-	-	-	-	-	-	-	533903-5
-	-	-	-	-	-	-	-	533903-4
-	M55302/173-24	48.26 [1.900]	19	52.07 [2.050]	62.23 [2.450]	69.85 [2.750]	40	533903-3
-	-	-	-	-	-	-	-	533903-2
-	-	-	-	-	-	-	-	533903-1

THIS DRAWING IS A CONTROLLED DOCUMENT. **TE** CONNECTIVITY

INCHES (DIMENSIONS IN BRACKETS ARE IN INCHES)

DATE: 100779

DRAWING NO: 533903

REVISED TO: 2

DATE: 4.1

BY: 2

APP: D2

PROJECT: HDI, 2 ROW, PIN ASSEMBLY, 4.83 [1.90] LONG SOLDER PINS, 00076 [0.00050] GOLD PLATE